



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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In re Application of:

Michael B. Ball and Jose L. Sanchez

Serial No.: 09/854,759

Filed: May 14, 2001

For: USING BACKGRIND WAFER TAPE
TO ENABLE WAFER MOUNTING OF
BUMPED WAFERS

Examiner: Unknown

Group Art Unit: 1734

Attorney Docket No.: 4589US (99-1151)

CERTIFICATE OF MAILING

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PRELIMINARY AMENDMENT

Box Non-Fee Amendment
Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to examination of the above-referenced patent application on the merits, entry of the amendments as set forth herein is respectfully solicited.

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